



WR01X

±5%, ±1%

Thick Film General Purpose chip resistors

Size 01005

*Contents in this sheet are subject to change without prior notice.



FEATURE

- 1. Ultra small and high precision size and light weight
- 2. High reliability and stability
- 3. Reduced size of final equipment
- 4. Suitable for high density print circuit board assembly
- 5. Higher component and equipment reliability
- 6. Lead free product

APPLICATION

- Mobile phone
- PDA, MP3, Ipod, iPHONE
- DSC, DVs
- Palmtop computers
- Mini module

DESCRIPTION

The resistors are constructed in a high grade ceramic body (aluminum oxide). Internal metal electrodes are added at each end and connected by a resistive paste that is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to nominated value within tolerance which controlled by laser trimming of this resistive layer.

The resistive layer is covered with a protective coat. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a pure Tin.



Fig 1. Construction of Chip-R WR01X



QUICK REFERENCE DATA

ltem	General Specification			
Series No.	WR01X			
Size code	01005 (0402)			
Resistance Range	4.7Ω ~ 1MΩ (±5	%, ±1%), Jumper		
Resistance Tolerance	±1%	±5%		
	E96/E24 E24			
TCR (ppm/°C)	100Ω - 1M Ω , $\leq \pm 200$ ppm			
	10Ω - 91Ω , $\leq \pm 300 \text{ ppm}$			
	4.7 - 9.1Ω, +600~ -200 ppm			
Max. dissipation @ T _{amb} =70°C	1/32 W			
Max. Operation Voltage (DC or RMS)	15V			
Max. Overload Voltage (DC or RMS)	30V			
Climatic category (IEC 60068)	55/125/56			

Note :

- 1. This is the maximum voltage that may be continuously supplied to the resistor element, see "IEC publication 60115-8"
- 2. Max. Operation Voltage : So called RCWV (Rated Continuous Working Voltage) is determined by

 $RCWV = \sqrt{RatedPower \times Resistance Value}$ or Max. RCWV listed above, whichever is lower.

DIMENSION(unit : mm)

	WR01X		
L	$\textbf{0.40} \pm \textbf{0.02}$		
w	$\textbf{0.20} \pm \textbf{0.02}$		
т	$\textbf{0.13} \pm \textbf{0.02}$		
Tb	$\textbf{0.10} \pm \textbf{0.03}$		
Tt	$\textbf{0.08} \pm \textbf{0.03}$		



MARKING

WR01X has no marking.

FUNCTIONAL DESCRIPTION

Product characterization

Standard values of nominal resistance are taken from the E24/E96 series for resistors with a tolerance of $\pm 5\%$ & $\pm 1\%$. The values of the E24/E96 series are in accordance with "IEC publication 60063"

Derating

The power that the resistor can dissipate depends on the operating temperature; see Fig.2



Figure 2. Maximum dissipation in percentage of rated power

As a function of the ambient temperature

MOUNTING

Due to its rectangular shape and ultra small size, Surface Mountable Resistors 01005 should be carefully handling by automatic placement systems. 01005 chip can withstand pressure force min. 1.9N by applying φ 0.18 pressure jig as shown drawing below. For mounting application, please contact Walsin group for details.



SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 245°C during 3 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 3.



Fig 3. Infrared soldering profile for Chip Resistors WR01X



CATALOGUE NUMBERS

The resistors have a catalogue number starting with :

WR01	X	472_	J	D	L
Size code	Type code	Resistance code	Tolerance	Packaging code	Termination code
WR01 : 01005	X : Normal W : 1%, < 10ohm	$\begin{array}{rrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrr$	J : ±5% F : ±1% P : Jumper	 D : 7" Reeled paper taping (20Kpcs/Reel) L : 7" Reeled embossed taping (35Kpcs/Reel) 	L = Sn base (lead free)



TEST AND REQUIREMENTS (JIS C 5201-1 : 1998)

TEOT		REQUIREMENT		
TEST	PROCEDURE / TEST METHOD	Resistor	0Ω	
DC resistance Clause 4.5	DC resistance values measured at the test voltages specified below : <10Ω@0.1V, <100Ω@0.3V, <1KΩ@1.0V, <10KΩ@3V, <100KΩ@10V, <1MΩ@25V, <10MΩ@30V	Within the specified tolerance	<50mΩ	
Temperature Coefficient of Resistance(T.C.R) Clause 4.8	Natural resistance change per change in degree centigrade. $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)} t_1 : 20^\circ\text{C}+5^\circ\text{C}-1^\circ\text{C}$ R ₁ : Resistance at reference temperature R ₂ : Resistance at test temperature	Refer to "QUICK REFERENCE DATA"	N/a	
Short time overload (S.T.O.L) Clause 4.13	Permanent resistance change after a 2 second application of a voltage 2.5 times RCWV or the maximum overload voltage specified in the above list, whichever is less.	∆R/R max. ±(1%+0.05Ω)	<50mΩ	
Resistance to soldering heat(R.S.H) IEC 60068-2-58: 2004	Un-mounted chips completely immersed for 10±0.5 second in a SAC solder bath at $260^\circ\!C\pm\!5^\circ\text{C}$	Δ R/R max. ±(1%+0.05 Ω) no visible damage	<50mΩ	
Solderability IEC 60068-2-58: 2004	Un-mounted chips completely immersed for 2±0.3 second in a SAC solder bath at 235 $^\circ\!\!C$ ±5 $^\circ\!\!C$	95% coverage min., good tinni visible damage	ng and no	
Temperature cycling Clause 4.19	30 minutes at -55°C±3°C, 2~3 minutes at 20°C+5°C-1°C, 30 minutes at +125°C±3°C, 2~3 minutes at 20°C+5°C-1°C, total 5 continuous cycles	ΔR/R max. ±(1%+0.05Ω)	< 50mΩ	
Damp Heat (Load life in humidity) Clause 4.24	1000+48/-0 hours, loaded with RCWV or Vmax in humidity chamber controller at 40°C±2°C and 90~95% relative humidity,	Δ R/R max. ±(5%+0.10 Ω) no visible damage	< 50mΩ	
Load Life (Endurance) Clause 4.25	1000+48/-0 hours; loaded with RCWV or V_{max} in chamber controller 70±2°C, 1.5 hours on and 0.5 hours off	Δ R/R max. ±(5%+0.10 Ω) no visible damage	< 50mΩ	
Endurance at the upper category temperature	125°C, no load, 1000 hours	Δ R/R max. ±(5%+0.10 Ω) no visible damage	< 50mΩ	
Bending strength Clause 4.33	Resistors mounted on a 90mm glass epoxy resin PCB(FR4), bending once 3mm for 10sec.	No visual damage, Δ R/R max. \pm (1%+0.05 Ω)	< 50mΩ	
Adhesion Clause 4.32	Pressurizing force: 2N, Test time: 10±1sec.	No visual damage		

PACKAGING

1.

Paper Tape specifications (unit :mm)



Series No.	А	В	W	F	E
WR01X	0.45±0.03	0.24±0.03	8.00±0.20	3.50±0.05	1.75±0.10

Series No.	P1	P0	ΦD	t1	Т
WR01X	2.00±0.05	4.00±0.05	Φ 1.50 ^{+0.1} 0.0	0.31±0.03	0.36±0.03

2. Embossed Narrow Tape specifications (unit: mm)



Reel dimensions





Symbol	A	В	С	D
(unit : mm)	#400 0 · 0/ 4 F	ACO 0 · 1 / 0	12.010.2	Paper tape: 9.0+1/-0
	Ф180.0+0/-1.5	Ф60.0+1/-0	13.0±0.2	Emboss tape: 4.2±0.8

Taping quantity and Tape material

- -
- Chip resistors 20,000 pcs/reel, Paper tape. Chip resistors 35,000 pcs/reel, Embossed tape. -
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